



In re Applicant:

Ilya Karpov et al.

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Assignee:

**Intel Corporation** 

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

## REPLY TO PAPER NO. 03152005

Sir:

In response to the office action mailed March 21, 2005, please amend the abovereferenced patent application as follows:

Date of Deposit: May 24, 2005

I hereby certify under 37 CFR 1.8(a) that this correspondence is being deposited with the United States Postal Service as **first class** mail with sufficient postage on the date indicated above and is addressed to the Commissioner for Patents, P.O. Box 1450,

Alexandria, VA 22313-1*45*0.

Cynthia V. Hayden